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(54) Title: CLEANING COMPOSITIONS AND METHODS OF USE THEREOF

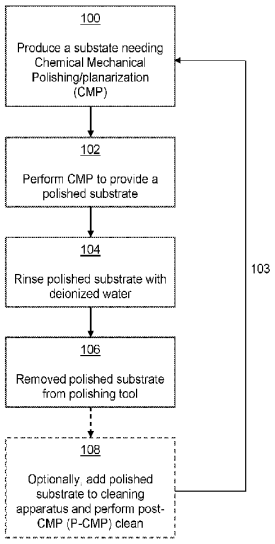


FIG. 1

(57) Abstract: The present disclosure relates to cleaning compositions that can be used to clean semiconductor substrates. These cleaning compositions can be used to remove defects arising from previous processing steps on these semiconductor substrates. These cleaning compositions can remove the defects/contaminants from the semiconductor substrates and thereby make the substrates appropriate for further processing. Such cleaning compositions can include use of a polisher rinse composition, use of a post-CMP composition, or use of a combination of the polisher rinse composition and the post-CMP composition.

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